

金居開發股份有限公司

Co-Tech Development Corp.

公司代號：8358

**2017年第三季法人說明會**

**Y17Q3 Earnings Conference**

## 2017年Q3營運績效

# 合併營運成果

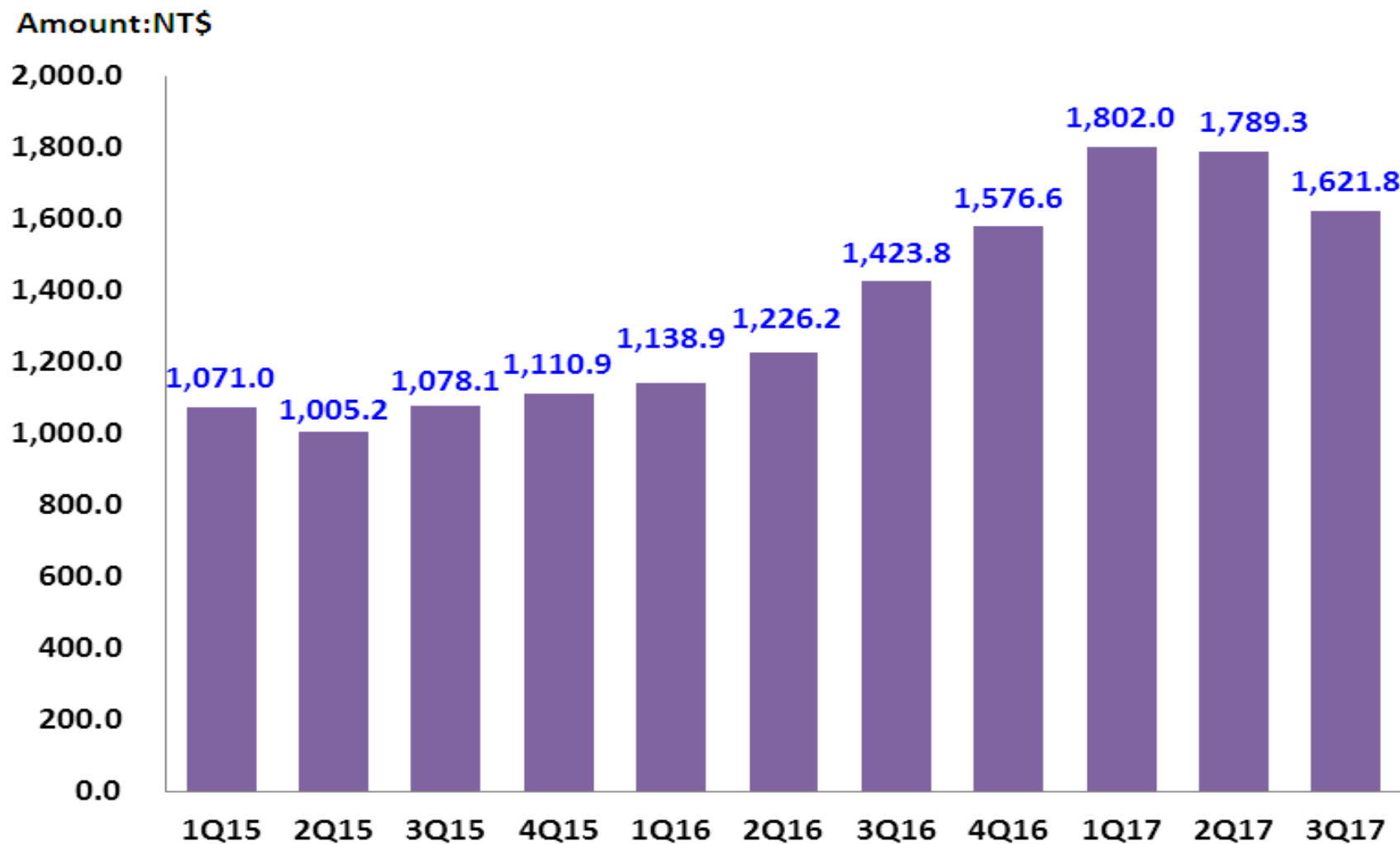
## Y17Q3 Results

Unit: NT\$ M	2017Q2		2017Q3				2016Q3			
	Act	%	Act	%	Delta	QoQ %	Act	%	Delta	YoY %
NSB	1,789.3	100.0	1,621.8	100.0	(167.5)	(9.4)	1,423.8	100.0	198.0	13.9
COGS	(1,286.0)	(71.9)	(1,268.6)	(78.2)			(1,148.2)	(80.6)		
GP	503.3	28.1	353.2	21.8	(150.1)	(29.8)	275.6	19.4	77.6	28.2
OPEX	(87.9)	(4.9)	(77.3)	(4.8)			(72.5)	(5.1)		
OP	415.4	23.2	275.9	17.0	(139.5)	(33.6)	203.1	14.3	72.8	35.8
OIOE	(14.4)	(0.8)	(14.9)	(0.9)			(33.6)	(2.4)		
PBT	401.0	22.4	261.0	16.1	(140.0)	(34.9)	169.5	11.9	91.5	54.0
TAX	(54.2)	(3.0)	(47.5)	(2.9)			(0.7)	0.0		
PAT	346.8	19.4	213.5	13.2	(133.3)	(38.4)	168.8	11.9	44.7	26.5
PAT to CO-TECH	352.9		216.6				183.9			
EPS	\$1.68		\$1.00				\$0.87			

# 合併營運成果

## Y17 Q1~Q3 Results

Unit: NT\$ M	2017Q1~Q3		2016Q1~Q3		Delta	YoY %
	Act	%	Act	%		
NSB	5,213.1	100.0	3,819.3	100.0	1,393.8	36.5
COGS	(3,836.1)	(73.6)	(3,229.5)	(84.6)		
GP	1,377.0	26.4	589.8	15.4	787.2	133.5
OPEX	(260.6)	(5.0)	(180.5)	(4.7)		
OP	1,116.4	21.4	409.3	10.7	707.1	172.8
OIOE	(54.6)	(1.0)	(74.1)	(1.9)		
PBT	1,061.8	20.4	335.2	8.8	726.6	216.8
TAX	(171.5)	(3.3)	(7.3)	(0.2)		
PAT	890.3	17.1	327.9	8.6	562.4	171.5
PAT to CO-TECH	916.2		352.4			
EPS	\$4.31		\$1.67			

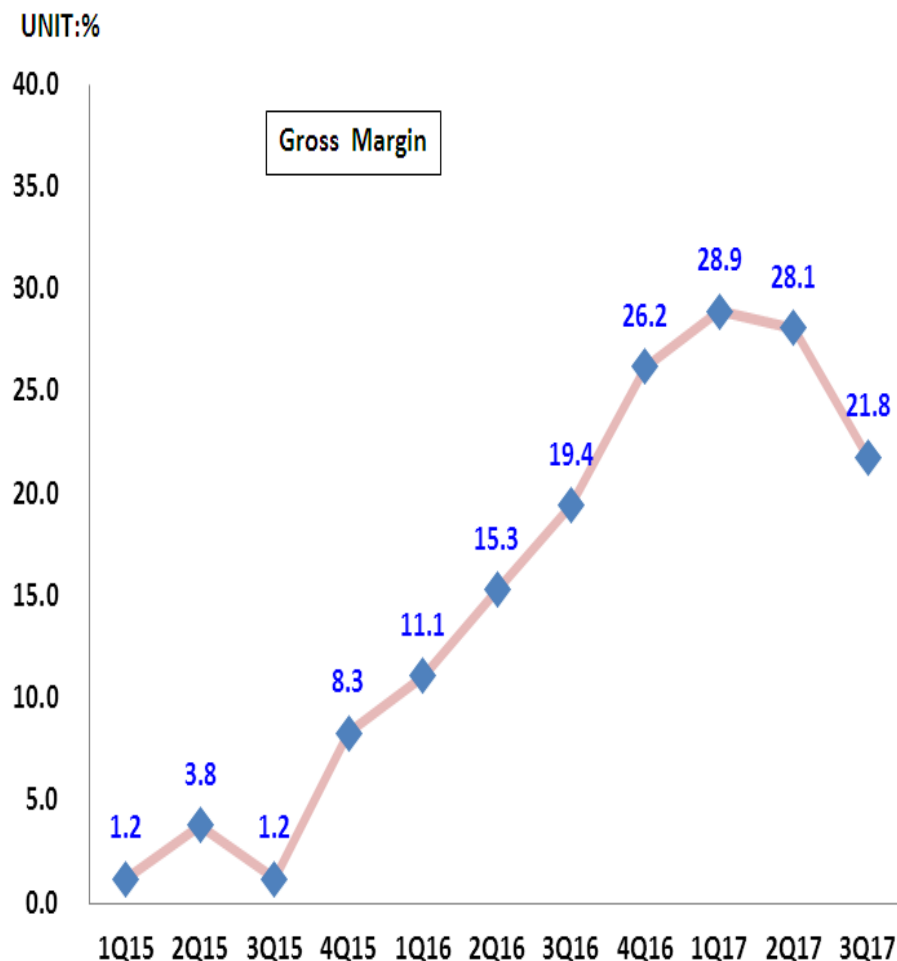
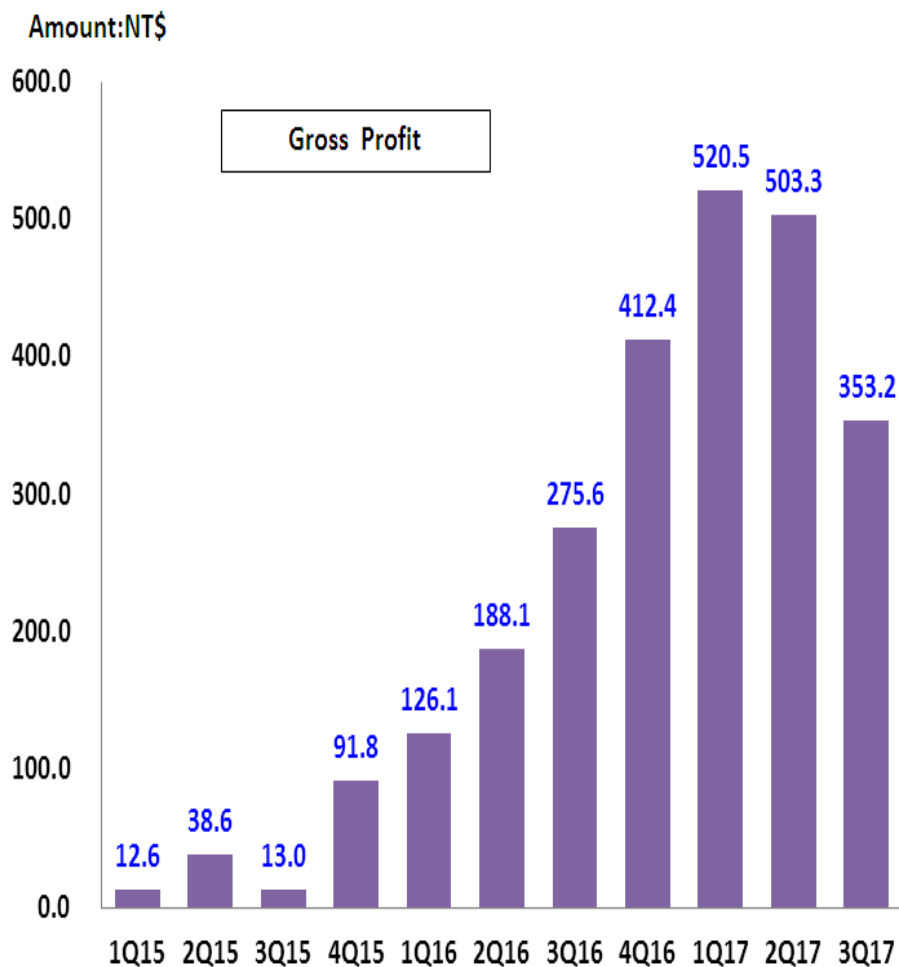




the copper foil solution provider

# 合併季營業毛利 & 營業毛利率

## Gross Profit & Gross Margin





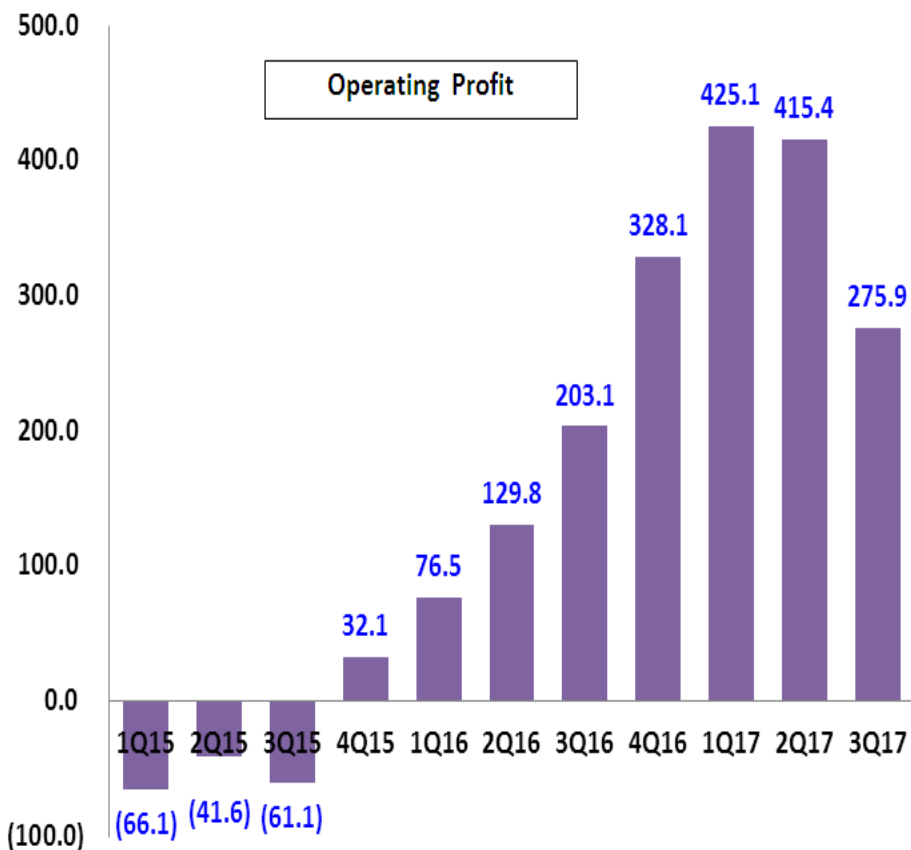
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# 合併季營業淨利 & 營業淨利率

## Operating Profit & Operating Margin

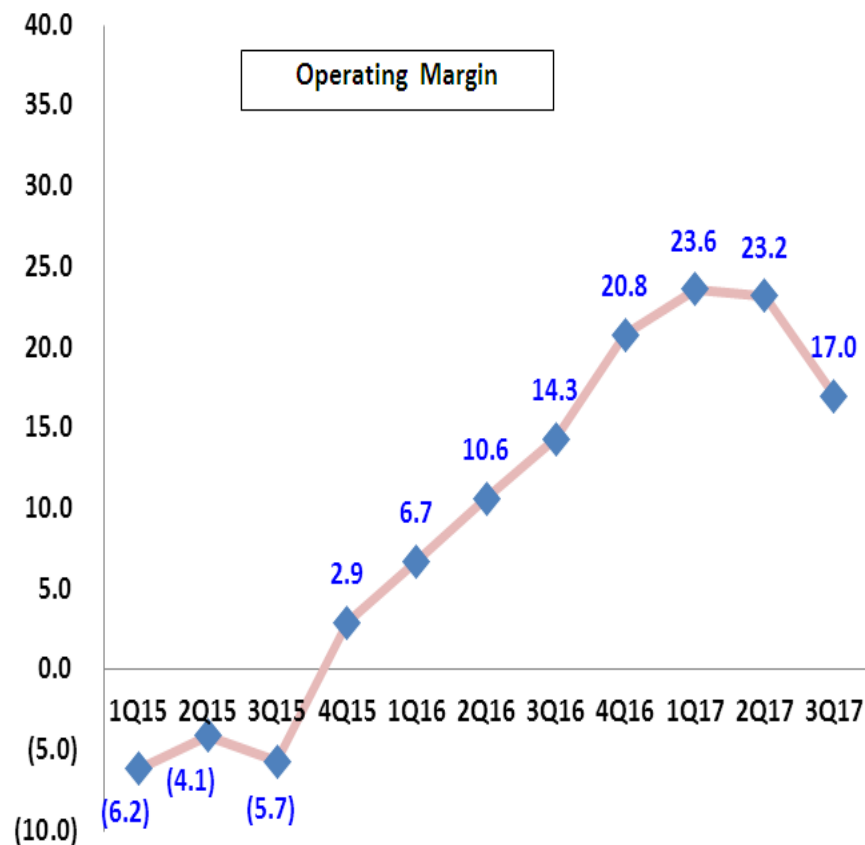
Amount:NT\$

Operating Profit



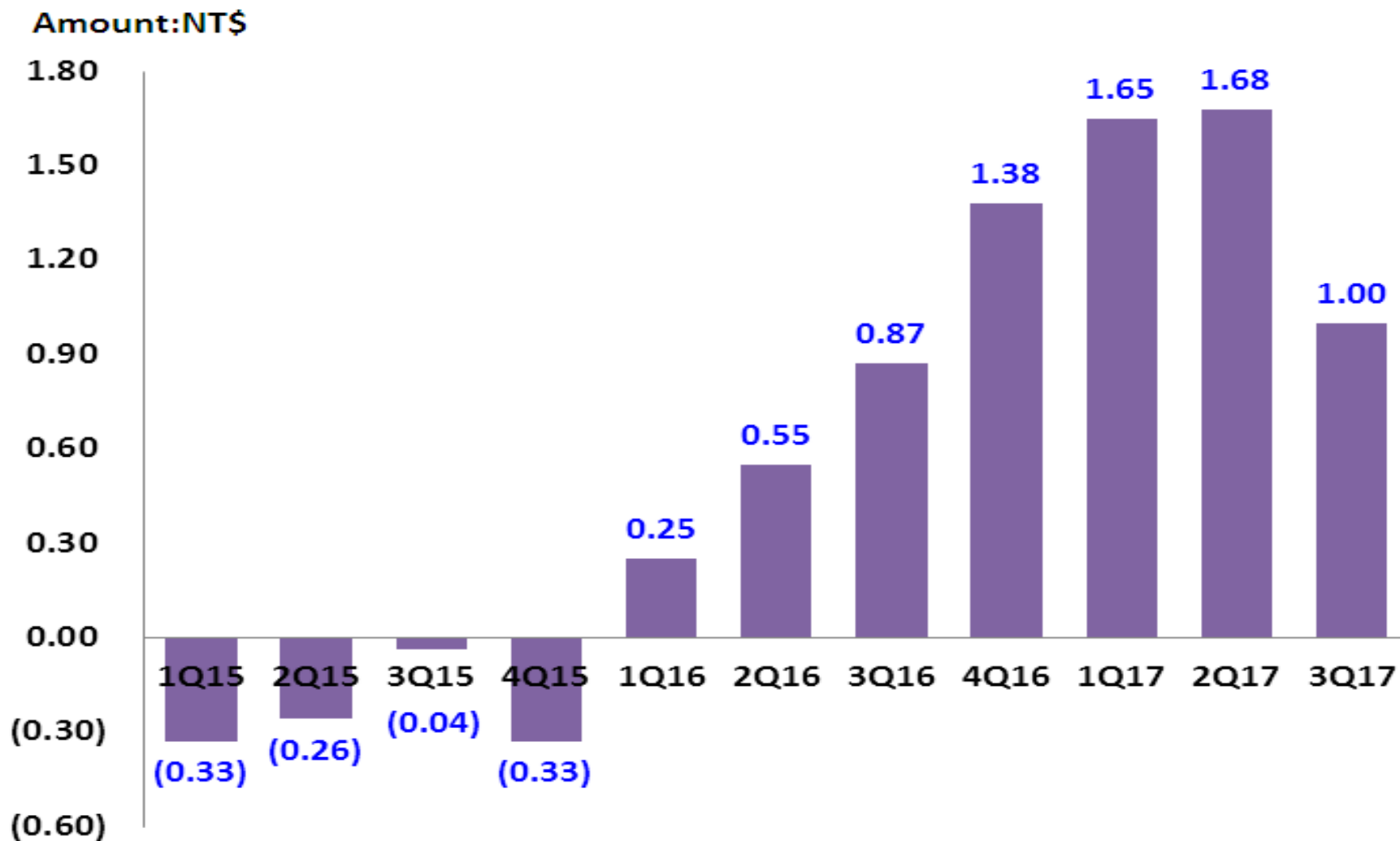
UNIT:

Operating Margin



## 合併季每股盈餘

## EPS





# 合併資產負債表

## Y17Q3 Balance Sheet

Unit : NT\$ M	Y17Q3		Y16Q4		Y16Q3	
	Amt	%	Amt	%	Amt	%
Cash	3,798	44	713	12	287	6
Accounts receivable	1,704	20	1,782	31	1,564	30
Inventory	426	5	396	7	380	7
Total Current Assets	6,084	71	3,000	52	2,378	46
<b>Total Assets</b>	<b>8,583</b>	<b>100</b>	<b>5,727</b>	<b>100</b>	<b>5,191</b>	<b>100</b>
S-T Borrings	2,203	26	1,560	27	1,389	27
Accounts payable	304	4	138	2	116	2
Total Current Liabilities	3,107	36	2,069	36	1,791	35
L-T Liabilities	344	4	1,452	25	1,462	28
<b>Total Liabilities</b>	<b>3,451</b>	<b>40</b>	<b>3,521</b>	<b>61</b>	<b>3,253</b>	<b>63</b>
<b>Total Equity</b>	<b>5,132</b>	<b>60</b>	<b>2,206</b>	<b>39</b>	<b>1,938</b>	<b>37</b>
<b>Key Indices</b>						
Current Ratio	1.96		1.45		1.33	
Quick Ratio	1.80		1.23		1.09	
Inventory Turnover(days)	29		35		35	
AR Turnover(days)	92		106		102	

# 簡報內容

## 公司近況說明

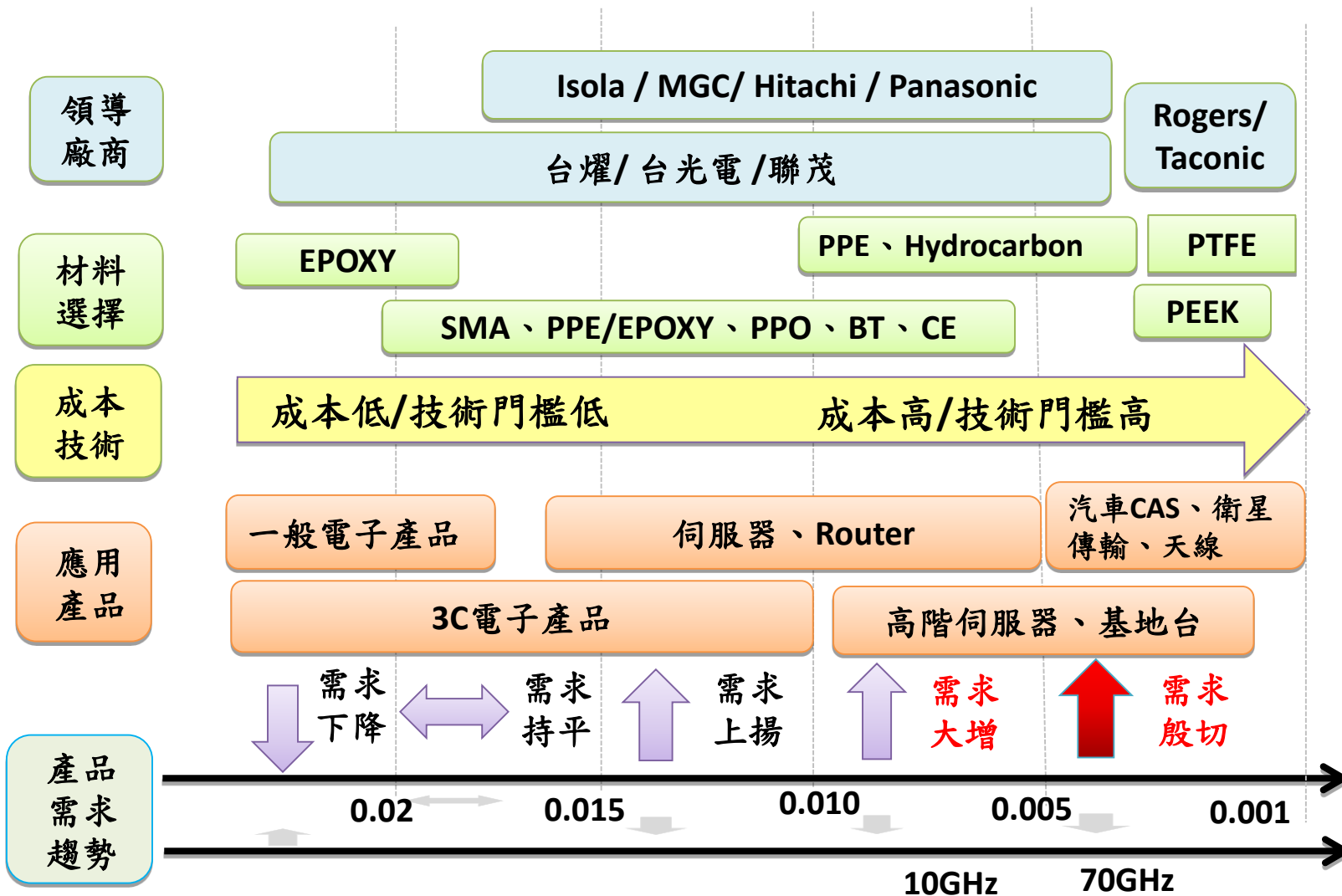
- 106年 7月 榮獲「櫃買富櫃五十指數」成分股  
Listed on TPEX 50 index
- 106年 9月 通過經濟部產業升級創新平台「5G產業高值化材料高頻用超低粗糙度銅箔」  
Subject of “5G high frequency very low profile copper foil” approved by industrial upgrade platform of Ministry of Economic Affairs.
- 106年10月 榮獲經濟部頒發「金貿獎」最佳貿易貢獻獎(金屬類)  
Won Golden Trade Award by Ministry of Economic Affairs
- 106年11月 金居納入「MSCI小型指數成分股」  
Listed on MSCI index

# 金貿獎

- 金居榮獲經濟部頒發「金貿獎」最佳貿易貢獻獎(金屬類)，由國貿局楊局長親自頒獎



## 2020年需求情境及國內外產業技術現況





**Co-Tech**  
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# 一代電子材料決定一代產品

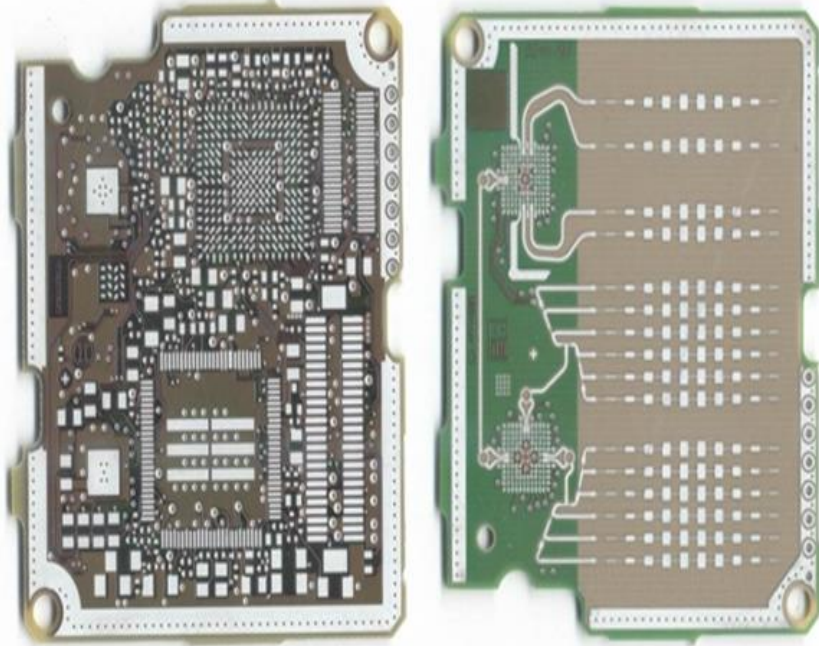
## “最佳化應用”的銅箔製造及服務業者

Copper foil manufacturing and service providers of application optimization

· 高速傳輸電路板及高頻無線網路產品，如基地台天線、伺服器、行動通訊、汽車雷達

· 軟板銅箔

· 鋰電池銅箔



Application Example for Mobile Terminal



Application Example for Automobile



## ➤ 高頻基板： (High frequency substrate)

高頻用超低損耗的基板材料開發，必須搭配超低粗糙度銅箔，現有的客戶群(如日系、台系、陸系等CCL大廠)已進行認證測試。

## ➤ 軟板： (FPCB)

韓國的最大的軟板FCCL 供應商已認證通，從2017/5已經開始供貨。

## ➤ 鐵氟龍基板： (PTFE substrate)

因應5G基地台於2020發酵，目前正與美國、大陸知名廠商開發鐵氟龍基板專用銅箔。

## ➤ 厚銅箔： (Heavy gauge foil)

應用於汽車、伺服器、UPS等大功率電源。